



Material Composition Sheet

Product: GS1503BCVE2
Package Type: 16x16mm 144 pin TQFP leadfree
Manufacturer: Gennum Corporation

Date: 06-Dec-2006

Component	BOM	Weight of Component (mg)	Substance	Weight of Substance (mg)	Homogeneous Material	
					%	ppm
Die		31.14	Polyimide	0.54	1.73	17341
			Si	30.60	98.26	982659
			Sub-total:	31.14	99.99	1000000
Die Attach		12.78	Ag	11.00	86.07	860720
			Epoxy Resin	1.38	10.79	107981
			Phenol Resin	0.40	3.12	31299
			Sub-total:	12.78	99.98	1000000
Lead Finish External		12.32	Bi	0.32	2.59	25974
			Sn	12.00	97.40	974026
			Sub-total:	12.32	99.99	1000000
Leadframe		163.43	Ag	4.20	2.56	25699
			Cu	152.00	93.00	930062
			Ni	5.00	3.05	30594
			Si	0.28	0.17	1713
			Sn	1.60	0.97	9790
			Zn	0.35	0.21	2142
			Sub-total:	163.43	99.96	1000000
Marking Ink		0.01		0.00	0.00	0
			Sub-total:	0.00	0.00	0
Mold Compound		451.40	BrominatedEpoxyResin	4.30	0.95	9526
			Carbon Black	6.60	1.46	14621
			Epoxy Resin	21.00	4.65	46522
			Organophosphorus compound	2.20	0.48	4874
			Phenol Resin	17.00	3.76	37661
			Sb302	4.30	0.95	9526
			SiO2 amorphous	375.00	83.07	830749
			SiO2 crystalline	21.00	4.65	46522
			Sub-total:	451.40	99.97	1000001
Wires		2.80	Au	2.80	100.00	1000000
			Sub-total:	2.80	100.00	1000000
Total:		673.88				

GENNUM CORPORATION

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